



SLOVENSKI STANDARD
SIST EN IEC 60747-16-9:2025

01-januar-2025

Polprevodniški elementi - 16-9. del: Mikrovalovna integrirana vezja - Fazni menjalniki (IEC 60747-16-9:2024)

Semiconductor devices - Part 16-9: Microwave integrated circuits - Phase shifters (IEC 60747-16-9:2024)

Halbleiterbauelemente - Teil 16-9: Integrierte Mikrowellenschaltungen - Phasenschieber (IEC 60747-16-9:2024)

Dispositifs à semiconducteurs - Partie 16-9: Circuits intégrés hyperfréquences - Déphaseurs (IEC 60747-16-9:2024)

Ta slovenski standard je istoveten z: EN IEC 60747-16-9:2024

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ICS:

31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general
31.200	Integrirana vezja, mikroelektronika	Integrated circuits. Microelectronics

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en

EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN IEC 60747-16-9

November 2024

ICS 31.080.99

English Version

**Semiconductor devices - Part 16-9: Microwave integrated
circuits - Phase shifters
(IEC 60747-16-9:2024)**

Dispositifs à semiconducteurs - Partie 16-9: Circuits
intégrés hyperfréquences - Déphaseurs
(IEC 60747-16-9:2024)

Halbleiterbauelemente - Teil 16-9: Integrierte
Mikrowellenschaltungen - Phasenschieber
(IEC 60747-16-9:2024)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 60747-16-9:2024 (E)

European foreword

The text of document 47E/835/FDIS, future edition 1 of IEC 60747-16-9, prepared by TC 47X "Semiconductors and Trusted Chips Implementation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 60747-16-9:2024.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2025-11-30
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2027-11-30

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The text of the International Standard IEC 60747-16-9:2024 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standard indicated:

IEC 60747-16-1:2001 NOTE Approved as EN 60747-16-1:2002 (not modified)

IEC 60747-16-4:2004 NOTE Approved as EN 60747-16-4:2004 (not modified)

IEC 60747-16-6:2019 NOTE Approved as EN IEC 60747-16-6:2019 (not modified)

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60747-1	2006	Semiconductor devices - Part 1: General	-	-
+ A1	2010		-	-
IEC 60747-4	2007	Semiconductor devices - Discrete devices -- Part 4: Microwave diodes and transistors		-
+ A1	2017		-	-
IEC 61340-5-1	-	Electrostatics - Part 5-1: Protection of electronic devices from electrostatic phenomena - General requirements	EN IEC 61340-5-1	-
IEC/TR 61340-5-2	-	Electrostatics - Part 5-2: Protection of electronic devices from electrostatic phenomena - User guide	CLC/TR 61340-5-2	-

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IEC 60747-16-9

Edition 1.0 2024-10

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Semiconductor devices –
Part 16-9: Microwave integrated circuits – Phase shifters**

**Dispositifs à semiconducteurs –
Partie 16-9: Circuits intégrés hyperfréquences – Déphaseurs**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES –

Part 16-9: Microwave integrated circuits –
Phase shifters

FOREWORD

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IEC 60747-16-9 has been prepared by subcommittee 47E: Discrete semiconductor devices, of IEC technical committee 47: Semiconductor devices. It is an International Standard.

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Draft	Report on voting
47E/835/FDIS	47E/842/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

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The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

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